

5G mmWave: Multi-site RF Probe Cards Enable Lower Cost-of-Test in Mass Production

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TEST VISION SYMPOSIUM

Overview

- 5G Rollout Update
- mmWave in the Handset
- 5G Test Metrics
- Strategies in Characterization & Production
- Key Challenges Overcome

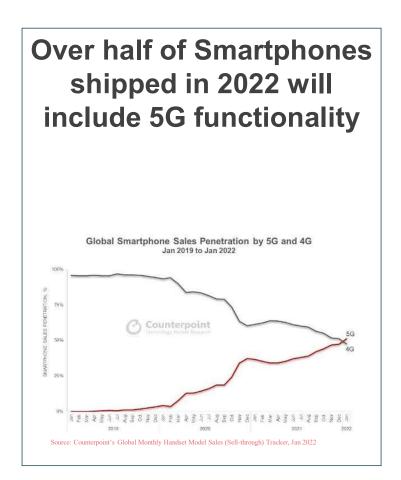


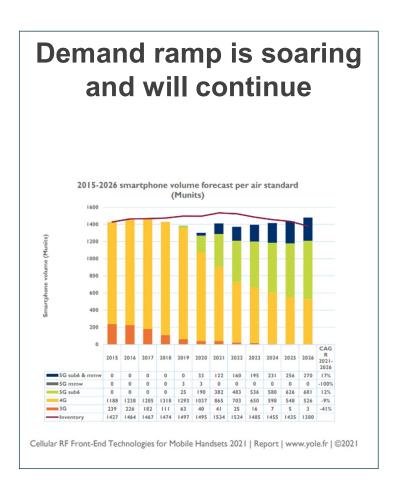




5G is Ramping...

The world's leading economies are actively deploying 5G coverage Source: CTS Corporation



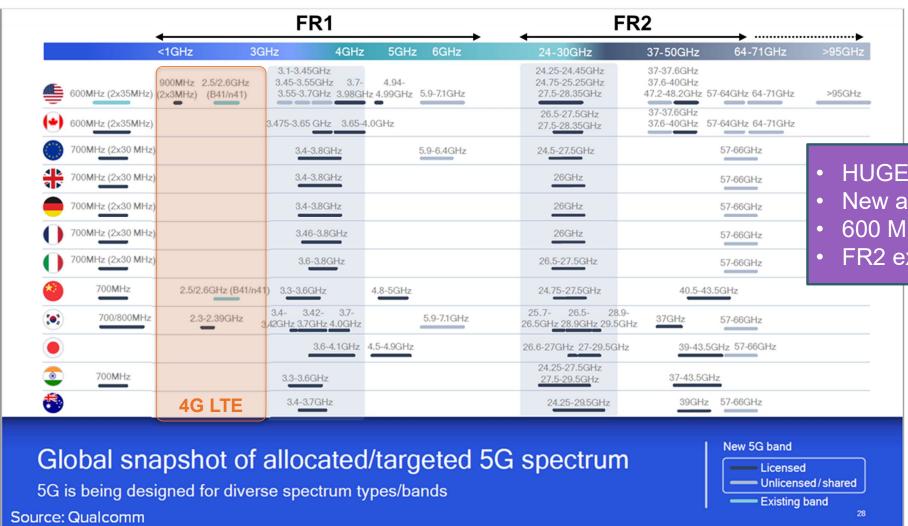








5G Frequency Spectrum Landscape





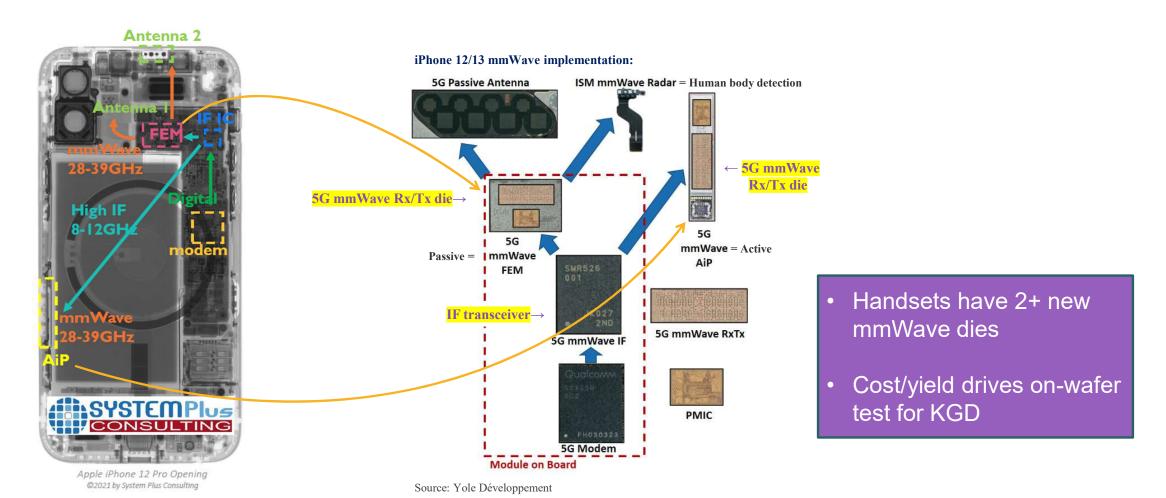
- HUGE increase in spectrum usage
- New allocations in all regions
- 600 MHz to >**71 GHz**
- FR2 extends 5G into mmWave







5G mmWave in the Handset



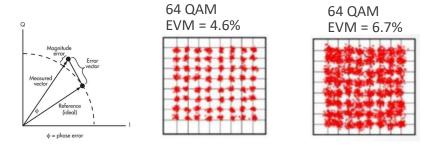


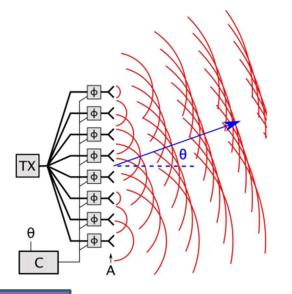




5G mmWave RxTx Test Metrics

- 5G mmW Rx/Tx die encode data by varying phase and amplitude of RF carrier
- Error Vector Magnitude (EVM) is key performance metric for RF transceivers, including 5G mmW Rx/Tx die
- Incredibly tight phase modulation is used to steer the transmission beam





- 5G mmW Transceiver module is the antenna which has unique test requirements
- → RF measurements need lab-grade for characterization and repeatability for production

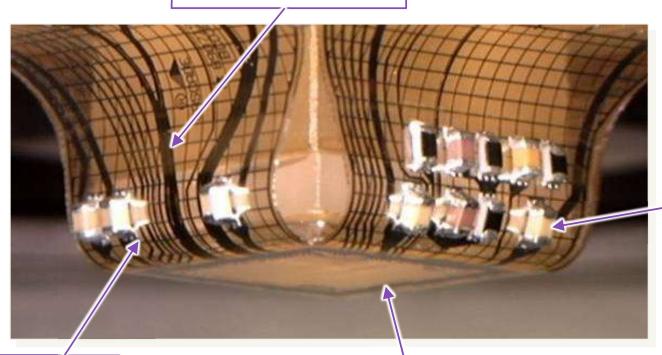






Pyramid Probe: Best Production On-wafer Signal Integrity





Bypass capacitors or components as little as 20 ps from the DUT

Low inductance power and ground to the probe tips

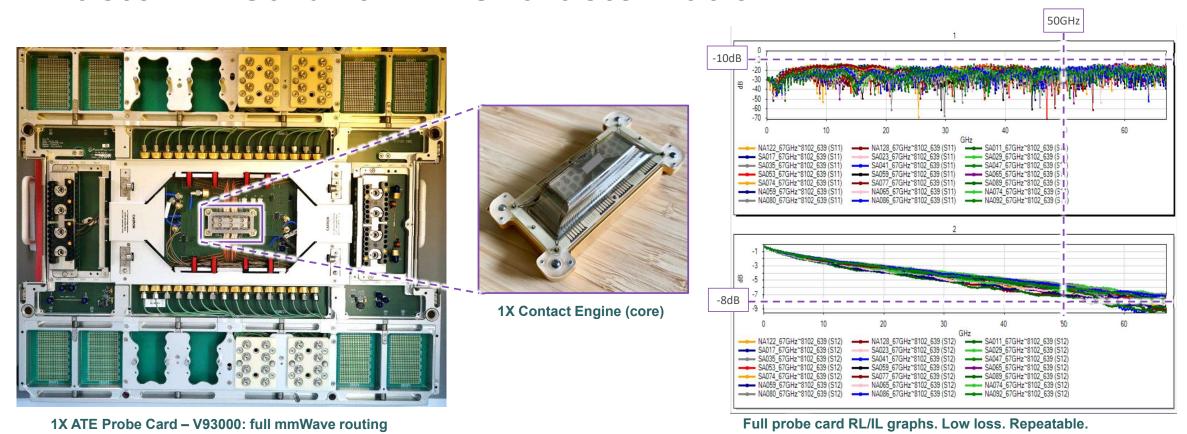
Low contact resistance <50 m Ω on solder







FormFactor x1 Card for RF Characterization



Pyramid probe cards have low RF loss and phase stability for accurate characterization of mmWave RxTx

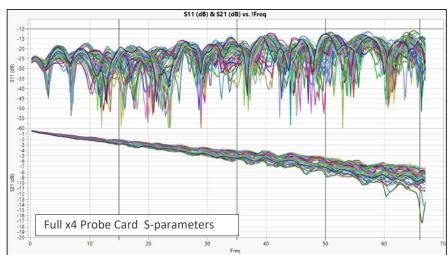


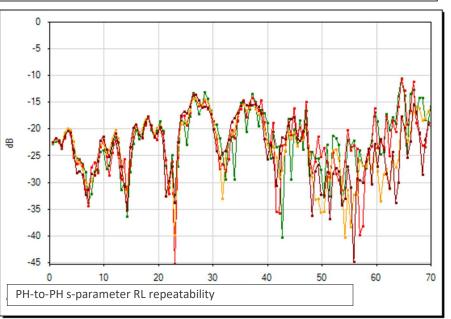




Consistent RF Performance

- Membrane fabrication tolerances = tight distribution of RF performance
 - Low site-to-site variation
 - Low card-to-card variation
 - Low touchdown to touchdown variation
 - Low loss by design
- Customers successfully use statistical techniques like NNR and Multivariate PAT to avoid rejecting good dies





Predictable RF performance = improved die yields





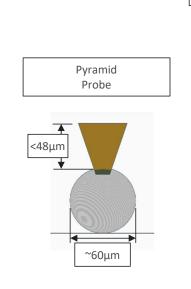


Pogo / vertical probe

Wavelength Matters

- At 55 GHz, 1 wavelength = 5.545mm
- Structures <u>below</u> 1/10 wavelength act like lumped elements
 - Pyramid tips are less than 1/100 wavelength → negligible
 - Minimal geometry changes vs. over travel and probe lifetime
- Structures above 1/10 wavelength act as distributed components
 - Pogo and vertical probes ~ ½ wavelength minimum (~2mm min length)
 - Phase shifts from touch-down to touch-down

Short probes are best for RF to achieve best performance





>2000µm



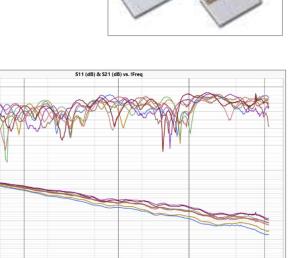




Consistency Leads to Effective De-embedding

- **De-embedding** defined:
 - Technique used to remove the effects of the probe card and test cell from the measured s-parameters leaving behind transmission qualities of the DUT
- Calibrated connector-to-probe-tip s-parameters measured infactory, then de-embedded from any measurement taken
 - anywhere
 - Customized RF test cell
 - Multipurpose calibration standard with SOL
 - 67 GHz VNA









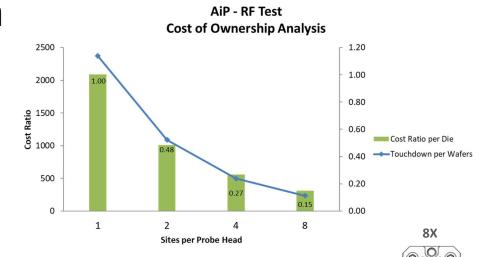


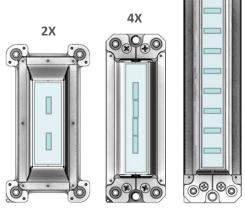
mmWave Device Test in Mass Production

- Production volume for 5G mmWave RxTx chips growing rapidly
 - 2019: 10M units
 - 2020: 75M units
 - 2021: 248M units*
 * from Yole Développement
- As volume goes up, cost of test must go down
- Probe cards with increased site parallelism enable cost reductions
 - But capitalize on gains by not scaling up mmWave interface and tester resources
- Cost of test is reduced by 63% using a 4X in production, and is the current state-ofthe-art for mmWave Production test



mmWave test accuracy and repeatability cannot be compromised.





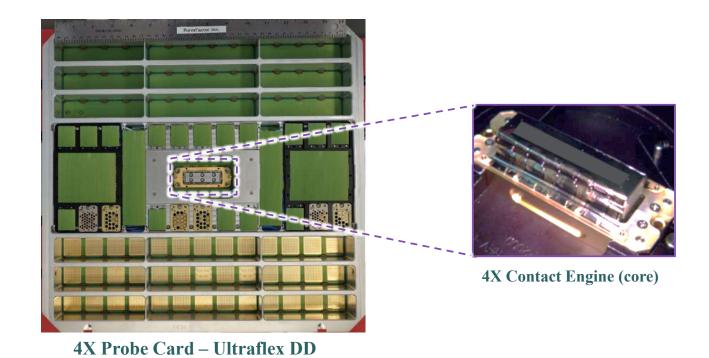
(Approx. to scale)

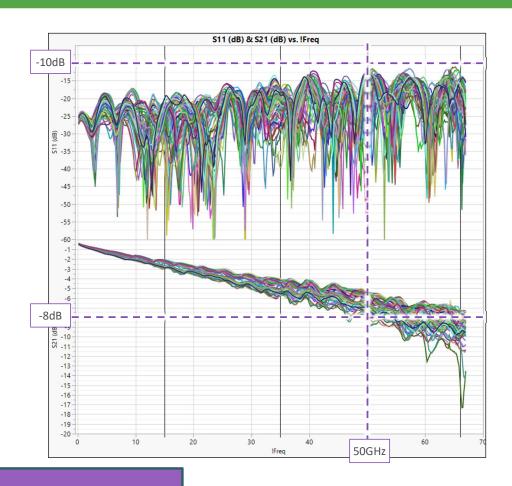






5G TxRx in HVM Production





Established 4X Pyramid Production Solution

- Volume production across multiple OSAT sites
- 100s of units shipped → > 300M dies tested and counting
- 128 mmWave lines per contact engine route from DUTs to tester

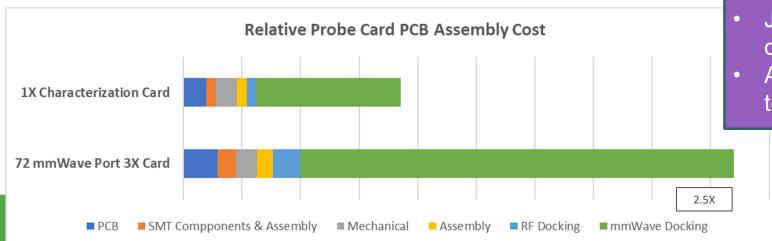






Cost Challenges of Increasing Test Parallelism

- Tester channel capability supports 3X testing max
 - V93000 Wave Scale Twinning has up to 72 ports at 67GHz (2X max //)
 - UltraFLEX UltraWave up to 96 ports at 67GHz (3X max //)
- Tester expense
 - mmWave ports are \$\$\$
- Probe card interface expense
 - At 1X, mmWave docking and interconnect is > 60% of overall probe card PCB cost
 - Cost scales linearly with number of interconnects



- Just adding tester resources is prohibitive due to \$\$\$\$.
- Alternative strategies needed to bring testing onto the probe card.

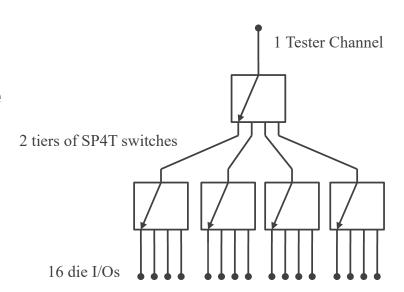


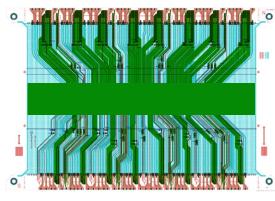




MUX Strategy to Extend Tester Capability

- RF signals onto PCB, RF Switch matrix to MUX/deMUX to one tester I/O
- Advantages
 - mmWave signals routed to tester
 - Full coverage of all I/O
- Disadvantages
 - Serial testing
 - High loss on PCB and in switches requires high dynamic range on tester I/O
- Challenges
 - Cutting edge RF switches are required
 - All mmWave lines need to be fully routed to PCB





All 128 mmWave lines routed to PCB









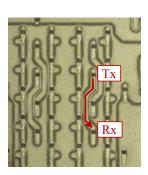
Loopback Approaches to Extend Tester Capability

PCB-level loopback

- Connect one or more I/O together on probe card PCB
- Can use attenuator to match power levels

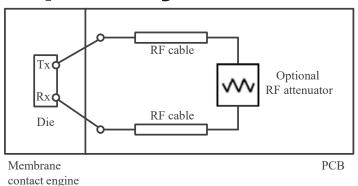
Probe Head loopback

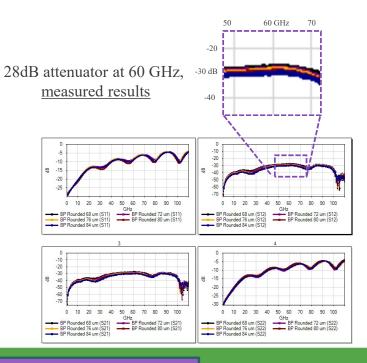
- Direct connect Tx to Rx at the die
- No power level matching
- Crosstalk a concern



Probe Head loopback with attenuation

- High performance microwave circuits built into the Pyramid head
- 3D field simulation = first time right



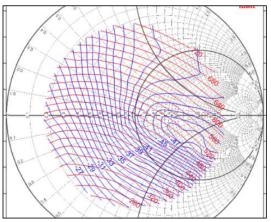






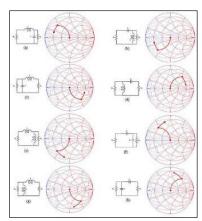
Unique Challenges of Testing an Antenna Driver

- Antenna input impedance is rarely 50Ω in target band
 - Varying input parameters can result in contour lines on the Smith chart
 - Matching PA output impedance to antenna impedance minimizes reflections back into the device

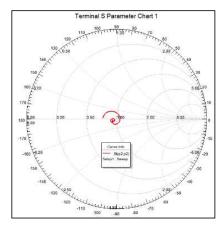


Typical Antenna input impedance optimization plot

- Pyramid Probe transmission lines can be matched to expected input impedance
 - Non-50Ω transmission lines
 - Complex impedance matching through discrete component networks
 - Impedance transitions in transmission lines
 - Transitions can occur very close to DUT



Complex impedance matching with discrete components



Transmission line impedance matching







Learnings from 4 Generations of Production Testing 5G mmWave RxTx:

Pyramid Probe Cards enable proven, best-in-class RF measurement through FR2 bands

128 RF lines @ 71 GHz

 mmWave test must be low loss and consistent across all sites, all cards, and all touchdowns

Improved die yields

MultiDUT testing is needed to hit cost and throughput targets

Reduced Cost of Test

 MUX and off-die loopback test strategies are used to extend tester resources in mmWave Rx/Tx production test

• 50Ω and non- 50Ω transmission lines improve antenna testing

Improved Test Value

Fundamental on-wafer probing challenges cannot be underestimated

Reliable



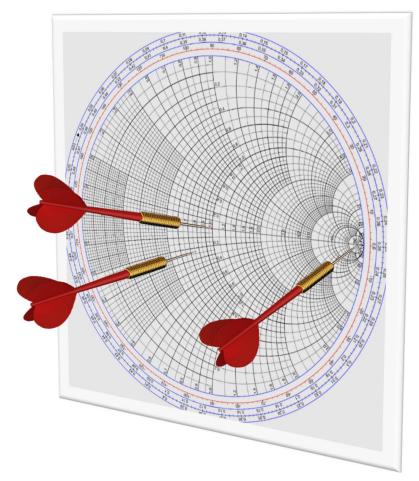




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Production mmWave Test Requires RF Mastery

